

Title (en)

HEAT SINK FOR AN ELECTRONIC COMPONENT AND METHOD FOR PRODUCING SAID HEAT SINK

Title (de)

KÜHLKÖRPER FÜR EINE ELEKTRONISCHE KOMPONENTE UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

DISSIPATEUR THERMIQUE POUR UN COMPOSANT ÉLECTRONIQUE ET SON PROCÉDÉ DE FABRICATION

Publication

**EP 3311407 A1 20180425 (DE)**

Application

**EP 16741270 A 20160708**

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Abstract (en)

[origin: WO2017029029A1] The invention relates to a heat sink (14) for an electronic component (12). The invention further relates to a method for producing such a heat sink. According to the invention, cooling chimneys (23) that open at the top are provided in the heat sink (14). Said cooling chimneys (23) are supplied with cooling air by cooling channels (21) (formed, for example, by an open-pore material having pores (19)), wherein said cooling air advantageously contributes to effective cooling of the electronic component (12). According to the invention, the air movement is produced by the stack effect in the cooling chimneys (23), and therefore no active components must be installed in the heat sink. The heat sink (14) can be produced, for example, by additive manufacturing methods, such as laser melting or laser sintering.

IPC 8 full level

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Citation (search report)

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